

-3535 5 2-0 4 -01 0

High Power LED chip size of 600 μm.

High Power

UV.

The package is certified and tested in accordance with the requirements.

GaN

GaN

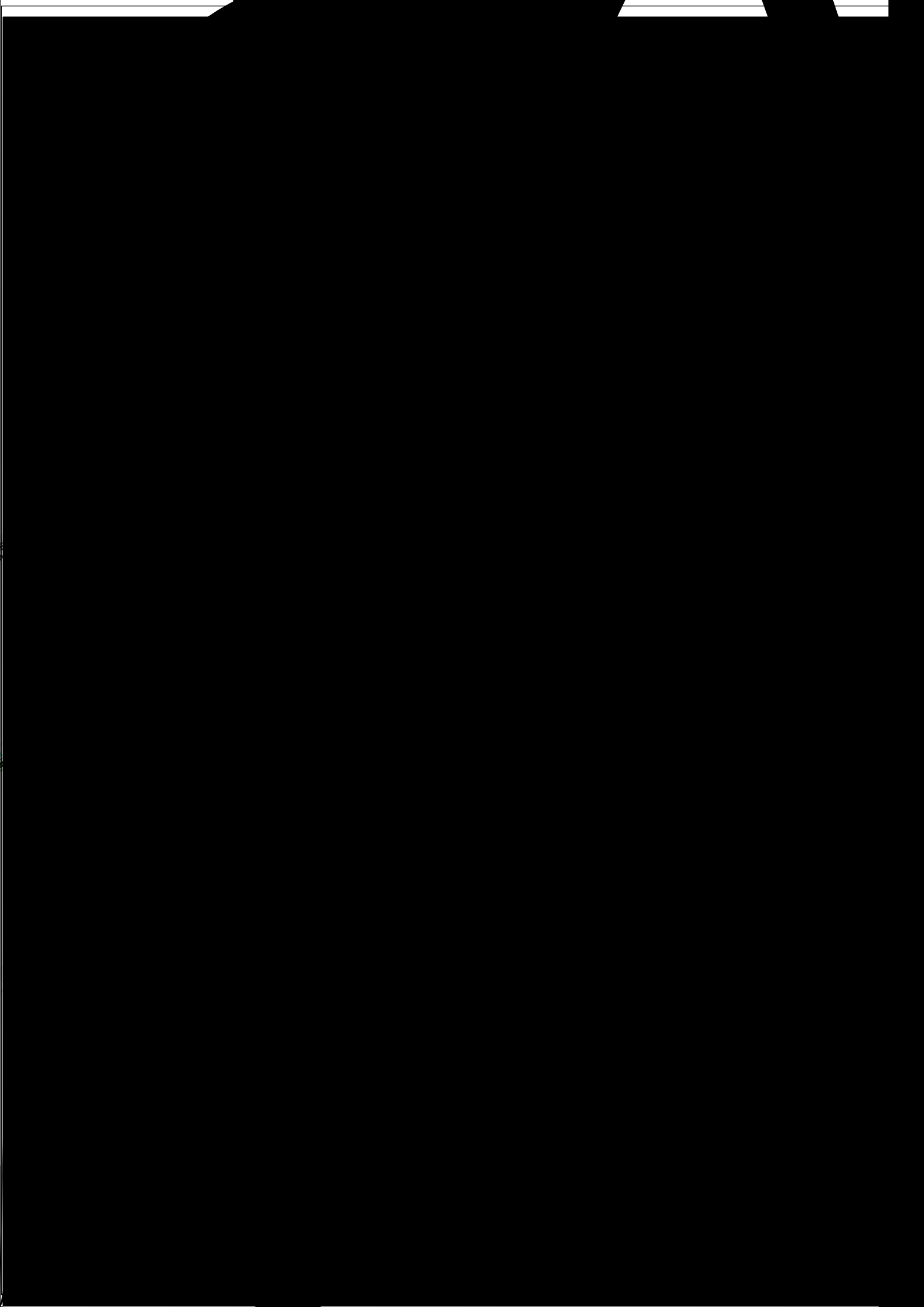
High Power (W)

High Power (S)

High Power

High Power

High Power



(25)

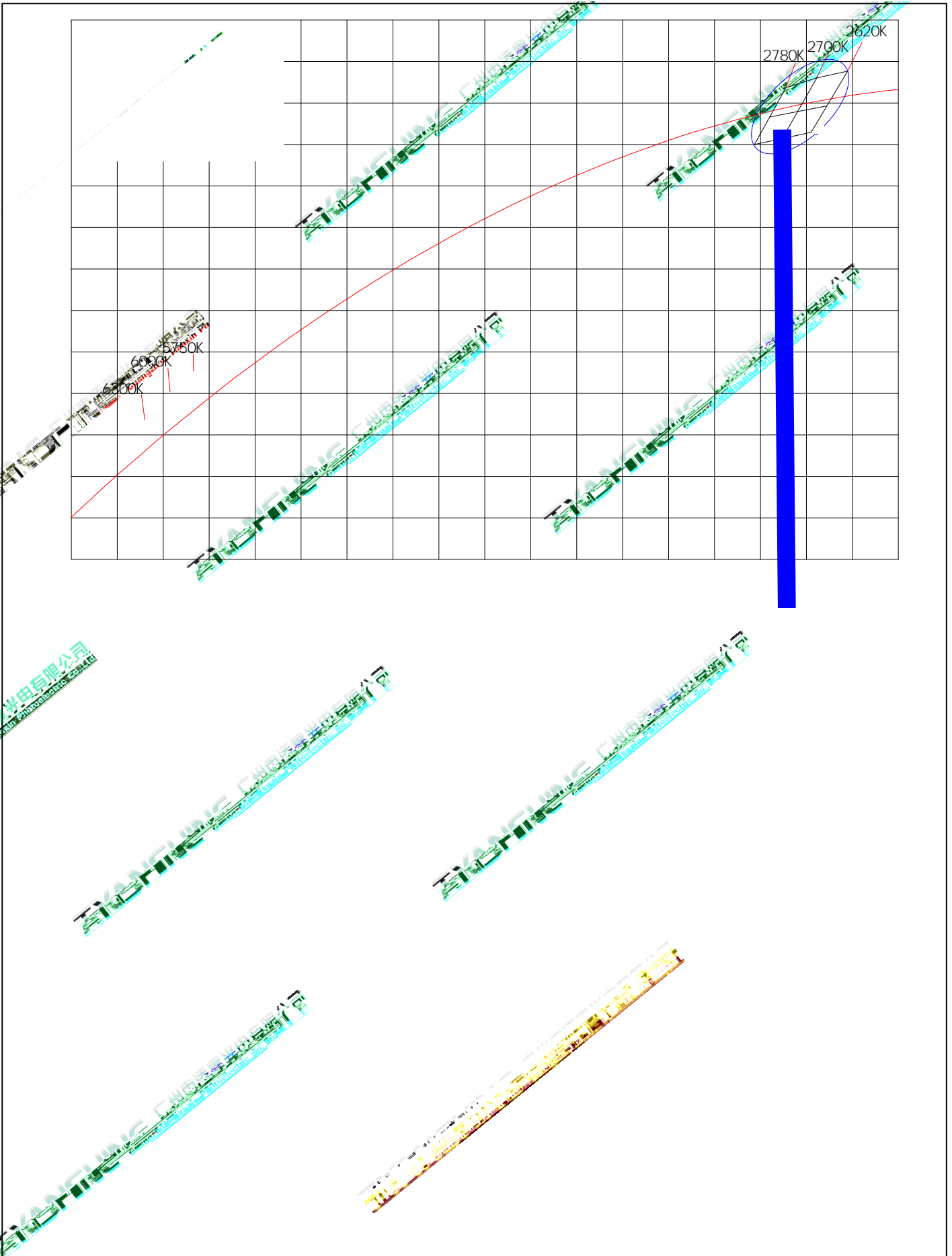
F adC e	IF	W	600	A
		S	600	
Re e eV lage	V _R	N de ig ed f e e e e ai		V
P e Di i ai	P _D	W	3660	W
		S	3660	
J c i Te e a e	T _J		150	
Elec a ic Di cha ge Th e h ld (ESD)	ESD		2000	V
DC Wi h a d lage e	V		1600	V
S age Te e a e	T _g		-40 +70	
O e ai Te e a e	T		-30 +85	

1. Specific storage charge in ice.
2. The data here specific if effective in the actual data in accordance with the actual lead.
3. Precaution for ESD:
STATIC SHIELD Electrostatic discharge for LED. It is recommended to use anti-static bags for LED. All devices, especially the lead, should be grounded.
4. The area of PCB cover is 3 times the lead area. If the area of each lead is 80% of the area of the lead, the area of the lead should be covered with 85%.

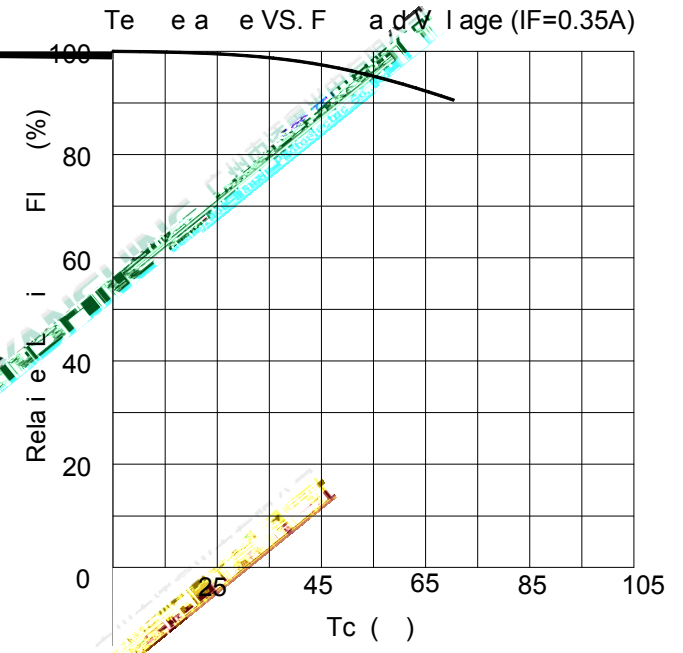
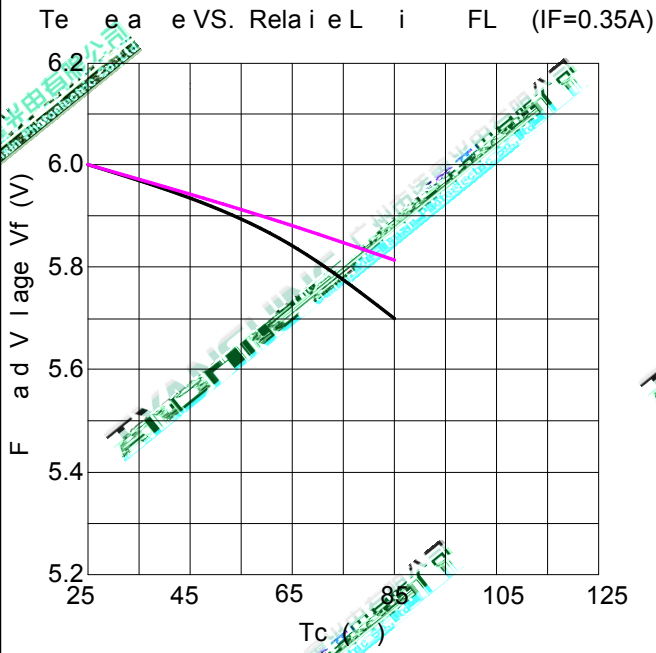
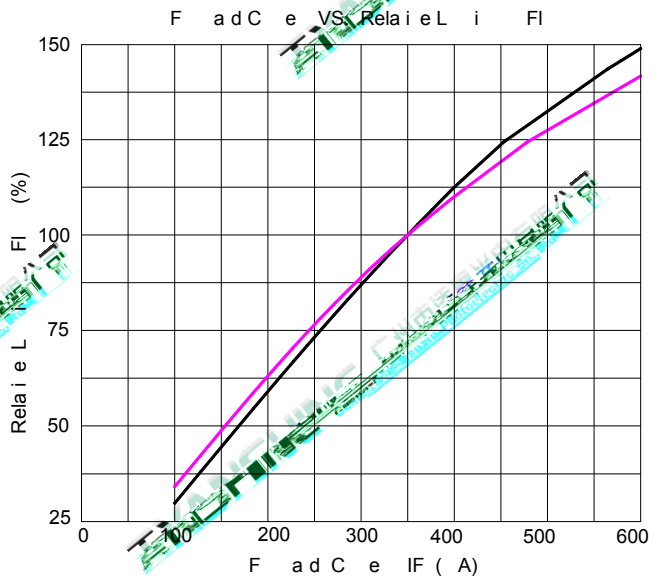
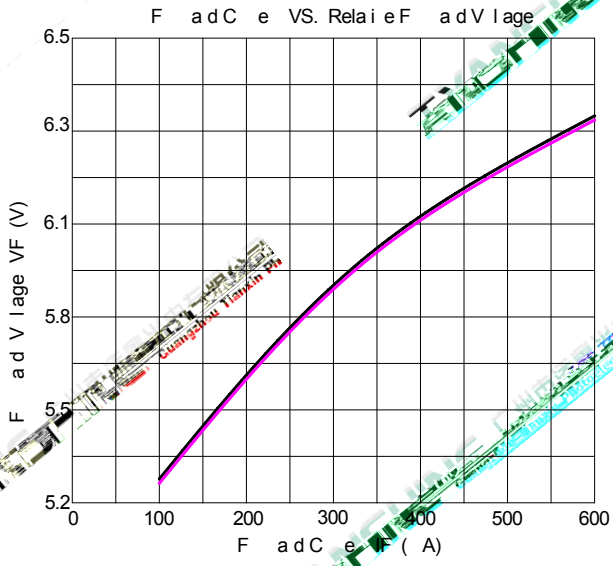
(25 350)

		W	25	350	S	
L i F l		W	180	210	240	I
		S	135	155	170	
C e l a e d C l T e e a e	CCT	W	5750	6000	6300	K
		S	2620	2700	2780	
C l R e d e i g l d e	Ra	W	90	92.5		
		S	90	92.5		
F a d V l a g e	V _f	W	5.8	6.0	6.2	V
		S	5.8	6.0	6.2	
V i e i g A g l e a 50 IV	2	W		120		Deg
		S		120		
Re e e C e	I _R					A
T h e r m a l R e i a c e C o c i C a e	R _{J-C}	W		5.0		K/W
		S		5.0		
T e e a e C e f f i c i e f V l a g e	V _{F/T}	W		-5		V/
		S		-3		

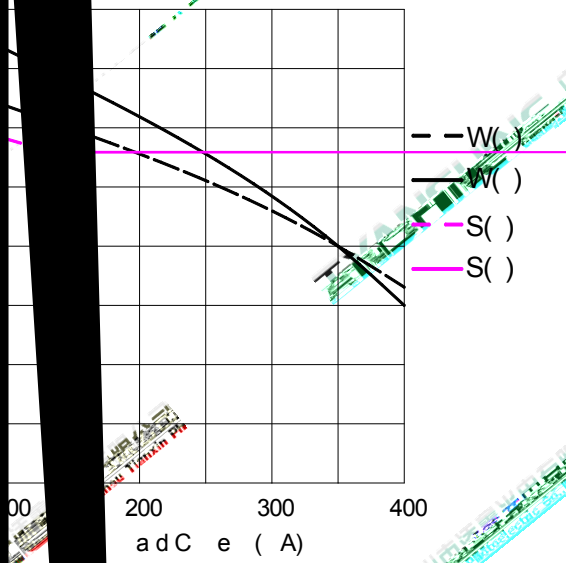
1. L i i e i i e a e d i h a l i g h e a d f i l e c b i a i h a a i a e h e C I E e e e e c e .
2. $1/2$ i h e f f a i a g l e a h i c h h e l i i e i i h a f h e a i a l l i i e i .
3. L i f l e a e e l e a c e : 10% .
4. F a d l a g e e a e e l e a c e : 10% V .
5. R a e a e e l e a c e : 2 .



(25 A bie Te ea eU le Ohe i eN ed)



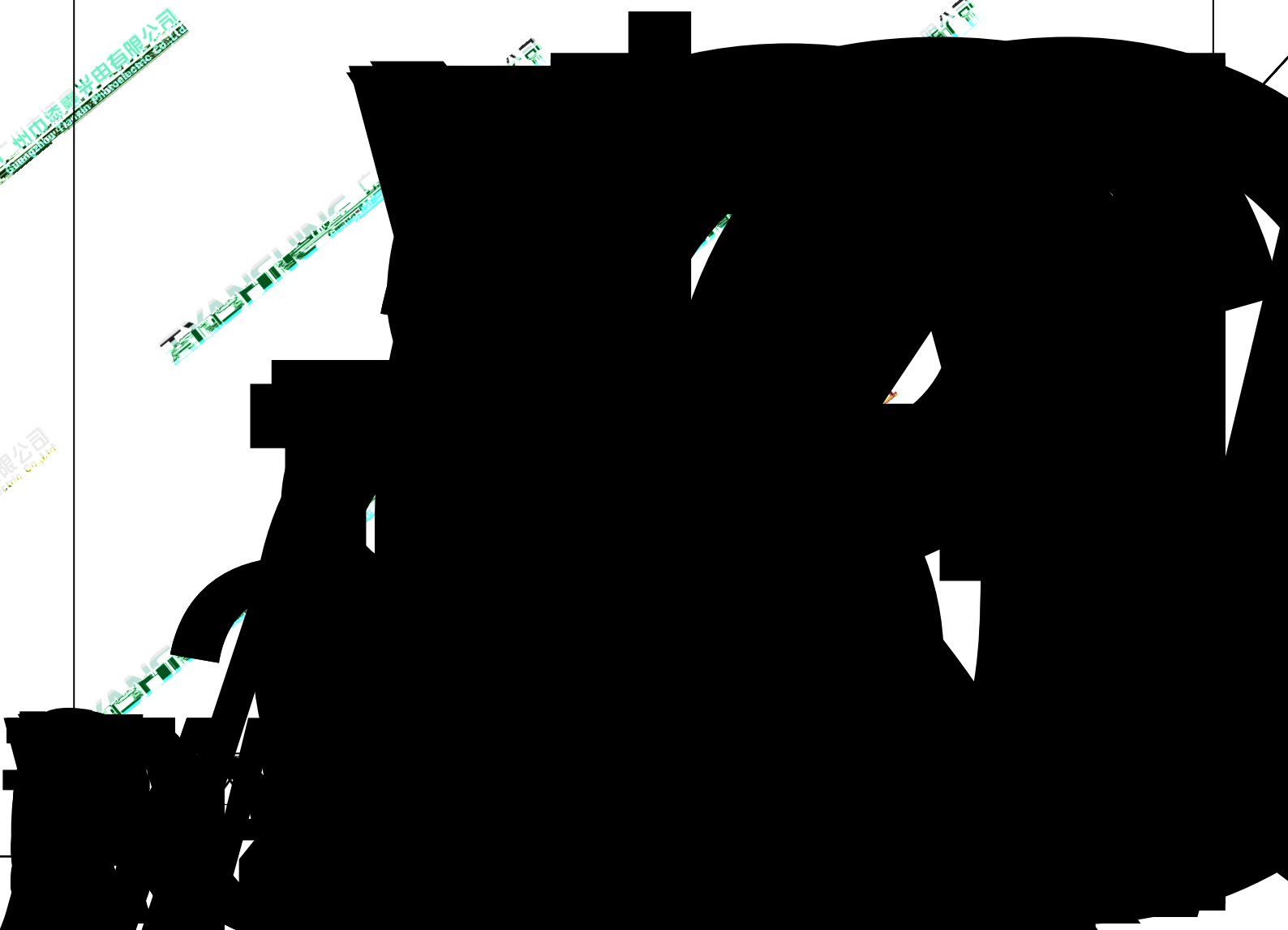
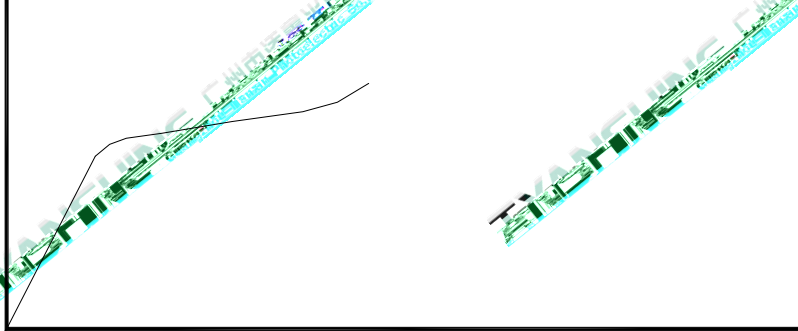
ieCh aici V.S.C e



Temperature: 5 30 (41 86)

Humidity: 60% RH Max.

Use these dimensions.



1000

